L Number	Hits	Search Text	DB	Time stamp
1	0	("(glassadjsubstratewithmethod).ti.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 10:34
2	304	glass adj substrate near4 method near4 (manufacturing).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 10:52
3	559	(65/111).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 10:52
4	7	((65/111).CCLS.) and (oxygen oxidiz$4) with (substrate substratum plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 10:54
5	3	((65/111).CCLS.) and (oxygen oxidiz$4) with (substrate substratum plate) and ion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 11:17
6	51125	("313").CLAS.	USPAT	2004/03/25 11:17
7	0	("6and"371").PN.	USPAT	2004/03/25 11:17
8	246	(("313").CLAS.) and "371"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 11:19
9	19	(("313").CLAS.) and "371" and pct	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:01
10	0	((65/111).CCLS.) and deactivat$4 near6 (substrate substratum plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:01
14	7691	(substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:15
15	3818	(substrate substratum sub adj stratum plate) with heat$5 with (celsius temperature centigrade "C") same ((oxygen air) adj atmosphere oxidiz$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:16
16	183	(substrate substratum sub adj stratum plate) with heat$5 with (celsius temperature centigrade "C") same ((oxygen air) adj atmosphere oxidiz$4) same oxidized with (metal metallic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:16
17	93	(substrate substratum sub adj stratum plate) with heat$5 with (celsius temperature centigrade "C") same ((oxygen air) adj atmosphere oxidiz$4) same oxidized near4 (metal metallic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:17
18	10	(substrate substratum sub adj stratum plate) with heat$5 with (celsius temperature centigrade "C") same ((oxygen air) adj atmosphere oxidiz$4) same oxidized near4 (metal metallic) and substrate near2 (glass silica)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:18

19	13	(substrate substratum sub adj stratum plate) with heat$5 with (celsius temperature centigrade "C") same ((oxygen air) adj atmosphere oxidiz$4) same oxidized near4 (metal metallic) and (substratum plate substrate) near2 (glass silica)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:18
20	13	((substrate substratum sub adj stratum plate) with heat$5 with (celsius temperature centigrade "C") same ((oxygen air) adj atmosphere oxidiz$4) same oxidized near4 (metal metallic) and (substratum plate substrate) near2 (glass silica)) and (substrate substratum sub adj stratum plate) with heat$5 with (celsius temperature centigrade "C") same ((oxygen air) adj atmosphere oxidiz$4) same oxidized near4 (metal metallic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:19
-	20034	ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in. matsushita-electric-industrial-co-ltd.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:41
-	564	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in. matsushita-electric-industrial-co-ltd.as.) and (etch$6) and glass near3 (substrate plate) and (tin Sn Mn manganese iron Fe In indium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:42
-	637	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in. matsushita-electric-industrial-co-ltd.as.) and (etch$6) and glass near5 (substrate plate) and (tin Sn Mn manganese iron Fe In indium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:42
-	14	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in. matsushita-electric-industrial-co-ltd.as.) and (etch$6) and glass near5 (substrate plate) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:43
-	8	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in. matsushita-electric-industrial-co-ltd.as.) and (etch$6) and glass near5 (substrate plate) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium)) and (silver Ag "Ag+")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:44
-	8	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in. matsushita-electric-industrial-co-ltd.as.) and (etch$6) and glass near5 (substrate plate) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium)) and (silver Ag "Ag+")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:57

-	7	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in. matsushita-electric-industrial-co-ltd.as.) and (etch$6) same (glass substrate) and glass near5 (substrate plate) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium)) and (silver Ag "Ag+")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:51
-	2	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in. matsushita-electric-industrial-co-ltd.as.) and (etch$6) same (glass substrate) and glass near5 (substrate plate) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium)) and (silver Ag "Ag+") near5 (electrode cathode anode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:02
-	2	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in. matsushita-electric-industrial-co-ltd.as.) and (etch$6) same (glass substrate) and glass near5 (substrate plate) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium)) and (silver Ag "Ag+") with (electrode cathode anode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 14:25
-	6173	(plasma adj display adj (display image panel) pdp).ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:51
-	0	(((65/111).CCLS.) and deactivat$4 near6 (substrate substratum plate)) and (hydrofluoric HF hydrogen adj fluoride) same (plate substrate) and (silver ag "Ag+") near6 electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:59
-	6173	(plasma adj display adj (display image panel) pdp).ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:59
-	1	((plasma adj display adj (display image panel) pdp).ab,ti,clm.) and (hydrofluoric HF hydrogen adj fluoride) same (plate substrate) and (silver ag "Ag+") near6 electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:52
-	0	masao-izumo.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:02
-	52	izumo-masao.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:41
-	6	izumo-masao.in. and (hydrogen fluoride hydrofluoric hf)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:04
-	52	izumo-masao.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:41

-	2	izumo-masao.in. and (hydrogen fluoride hydrofluoric hf) same (substrate plate) and (silver Ag "Ag+")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:42
-	6	izumo-masao.in. and (hydrogen fluoride hydrofluoric hf) same (substrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:42
-	6	izumo-masao.in. and (hydrogen fluoride hydrofluoric hf) same (substrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:44
-	2	izumo-masao.in. and (hydrogen adj fluoride hydrofluoric hf) same (substrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:51
-	6173	(plasma adj display adj (display image panel) pdp).ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:51
-	6	((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride) same (plate substrate) and (silver ag "Ag+") near6 electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 14:53
-	6	((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride) same (plate substrate) and (silver ag "Ag+") near6 electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:12
-	3	(((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride) same (plate substrate) and (silver ag "Ag+") near6 electrode) and (sulfuric chloric hcl sulphuric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:13
-	0	jp112462238.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:11
-	0	"112462238"	JPO	2003/09/16 15:11
-	0	"jp112462238"	JPO	2003/09/16 15:11
-	0	"jp0112462238"	JPO	2003/09/16 15:11
-	0	"jp1102462238"	JPO	2003/09/16 15:11
-	1	"jp10050519"	JPO	2003/09/16 15:11
-	7	((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride fluoric) same (plate substrate) and (silver ag "Ag+") near6 electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:16
-	1	(((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride fluoric) same (plate substrate) and (silver ag "Ag+") near6 electrode) not (((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride) same (plate substrate) and (silver ag "Ag+") near6 electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:12

-	0	((((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride fluoric) same (plate substrate) and (silver ag "Ag+") near6 electrode) not (((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride) same (plate substrate) and (silver ag "Ag+") near6 electrode)) and (sulfuric chloric hcl sulphuric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:13
-	1	((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride fluoric) same (plate substrate) and (silver ag "Ag+") near6 electrode and (colloid$5) near5 (silver Ag "Ag+")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:17
-	11	(hydrofluoric HF hydrogen adj fluoride fluoric) same (plate substrate) and (silver ag "Ag+") near6 electrode and (colloid$5) near5 (silver Ag "Ag+")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:18
-	11	(hydrofluoric HF hydrogen adj fluoride fluoric) with (plate substrate) and (silver ag "Ag+") near6 electrode and (colloid$5) near5 (silver Ag "Ag+")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:18
-	1	(hydrofluoric HF hydrogen adj fluoride fluoric) with (plate substrate) and (silver ag "Ag+") near6 electrode and (colloid$5) near5 (silver Ag "Ag+") and (sulfuric hcl chloric hydrochloric) same (plate substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:28
-	7	(hydrofluoric HF hydrogen adj fluoride fluoric) with (plate substrate) and (silver ag "Ag+") near6 electrode and (colloid$5) near5 (silver Ag "Ag+") and (sulfuric hcl chloric hydrochloric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:20
-	6	((hydrofluoric HF hydrogen adj fluoride fluoric) with (plate substrate) and (silver ag "Ag+") near6 electrode and (colloid$5) near5 (silver Ag "Ag+") and (sulfuric hcl chloric hydrochloric)) not (((plasma adj display adj (display image panel) pdp).bi.) and (hydrofluoric HF hydrogen adj fluoride fluoric) same (plate substrate) and (silver ag "Ag+") near6 electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:19
-	1	(hydrofluoric HF hydrogen adj fluoride fluoric) with (plate substrate) and (silver ag "Ag+") near6 electrode and (colloid$5) near5 (silver Ag "Ag+") and (sulfuric hcl chloric hydrochloric) same (hydrofluoric HF hydrogen adj fluoride fluoric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:20
-	80	((hydrofluoric HF hydrogen adj fluoride fluoric) (CaF1 Calcium adj fluoride aluminum adj fluoride AlF1 ammonium near2 fluoride near3 acid)) same (sulfuric hcl chloric hydrochloric) same (plate substrate) and (silver ag "Ag+") near6 electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:33
-	28	((hydrofluoric HF hydrogen adj fluoride fluoric) (CaF1 Calcium adj fluoride aluminum adj fluoride AlF1 ammonium near2 fluoride near3 acid)) same (sulfuric hcl chloric hydrochloric) same (plate substrate) and (silver ag "Ag+") near6 electrode and (panel display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:34
-	15	((hydrofluoric HF hydrogen adj fluoride fluoric) (CaF1 Calcium adj fluoride aluminum adj fluoride AlF1 ammonium near2 fluoride near3 acid)) same (sulfuric hcl chloric hydrochloric) same (plate substrate) same (mix$4) and (silver ag "Ag+") near6 electrode and (panel display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:38

-	6	((hydrofluoric HF hydrogen adj fluoride fluoric) (CaFl Calcium adj fluoride aluminum adj fluoride AlFl ammonium near2 fluoride near3 acid)) with (sulfuric hcl chloric hydrochloric) same (plate substrate) same (mix$4) and (silver ag "Ag+") near6 electrode and (panel display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:48
-	1	2001-285778.NRAN.	DERWENT	2003/09/16 15:43
-	947	float adj glass and (silver Ag "Ag+")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:07
-	131	(float adj glass and (silver Ag "Ag+")) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:50
-	2	((float adj glass and (silver Ag "Ag+")) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium))) and ((hydrofluoric HF hydrogen adj fluoride fluoric) (CaFl Calcium adj fluoride aluminum adj fluoride AlFl ammonium near2 fluoride near3 acid)) same (sulfuric hcl chloric hydrochloric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:51
-	2	((float adj glass and (silver Ag "Ag+")) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium))) and ((hydrofluoric HF hydrogen adj fluoride fluoric) (CaFl Calcium adj fluoride aluminum adj fluoride AlFl ammonium near2 fluoride near3 acid)) same (sulfuric hcl chloric hydrochloric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:52
-	27776	asahi-glass-co-ltd.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:53
-	679	asahi-glass-co-ltd.as. and (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:05
-	4	asahi-glass-co-ltd.as. and (silver Ag) and liquor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 15:58
-	0	2001048594.URPN.	USPAT	2003/09/16 15:59
-	1	2001-285778.NRAN.	DERWENT	2003/09/16 15:59
-	5	asahi-glass-co-ltd.as. and (silver Ag) and polish$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:05
-	0	2000226233.URPN.	USPAT	2003/09/16 16:06
-	113	float adj glass and (silver Ag "Ag+") and yellow near4 color$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:07
-	3	float adj glass and (silver Ag "Ag+") and yellow near4 color$6 near5 (prevent suppress supress)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:08
-	3	float adj glass and (silver Ag "Ag+") and yellow near4 color$6 near5 (prevent suppress supress)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:09

-	226	(silver Ag "Ag+") and yellow near3 color$6 with (susbstrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:10
-	22	(silver Ag "Ag+") near6 (electrode cathode anode) and yellow near3 color$6 with (susbstrate plate float adj glass)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:11
-	19	(silver Ag "Ag+") near6 (electrode cathode anode) and yellow near3 color$6 with (susbstrate plate float adj glass) and acid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:14
-	6	(silver Ag "Ag+") near6 (electrode cathode anode) and yellow near3 color$6 with (susbstrate plate float adj glass) and acid not polarizing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:18
-	0	(silver Ag "Ag+") near6 (electrode cathode anode) and yellow near3 color$6 with (susbstrate plate float adj glass) and acid same ($2fluor$5) not polarizing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:19
-	0	(silver Ag "Ag+") near6 (electrode cathode anode) and yellow near3 color$6 with (susbstrate plate float adj glass) and acid same ($3fluor$5) not polarizing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:19
-	2	(silver Ag "Ag+") near6 (electrode cathode anode) and yellow near3 color$6 with (susbstrate plate float adj glass) and acid same (sulfuric HFL) not polarizing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:31
-	2	(silver Ag "Ag+") near6 (electrode cathode anode) and yellow near3 color$6 with (susbstrate plate float adj glass) and reduc$5 with (silver ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 16:32
-	2	glass near5 (substrate plate) and ((tin Sn) and (Mn manganese) and (iron Fe) and (In indium)) and (silver Ag "Ag+") same (color$8) near10 yellow and (plasma adj display pdp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 18:39
-	172	parts near3 million near4 weight adj percent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 18:59
-	75	(reduc$7) same (metal metallic) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) not "l12" not "l15"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 15:12
-	75	(reduc$7) same (metal metallic) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) not "l12" not "l15"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 15:58
-	75	(reduc$7) same (metal metallic) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 15:30
-	35	(reduc$7) same (metal metallic) near3 ion same (substrate glass plate silica) with (heat$7 bak$8) same (oxygen oxidiz$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 15:35

-	17	(reduc$7) same (metal metallic) near3 ion same (substrate glass plate silica) with (heat$7 bak$8) same (oxygen oxidiz$5) same (degree "C" celsius)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 15:36
-	3	(US-4313748-$ or US-4220682-$ or US-4110096-$).did.	USPAT	2003/09/17 15:47
-	3	((US-4313748-$ or US-4220682-$ or US-4110096-$).did.) and glass with (plate substrate flat)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 15:48
-	1	(reduc$7) same (metal metallic) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and 4313748.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:06
-	33	(reduc$7) same (metal metallic) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:13
-	37	(reduc$7) same (metal metallic Tin Sn Manganese Mn Iron Fe Indium In) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:11
-	4	((reduc$7) same (metal metallic Tin Sn Manganese Mn Iron Fe Indium In) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and (silver Ag)) not ((reduc$7) same (metal metallic) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and (silver Ag))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:07
-	6	(reduc$7) same (Tin Sn Manganese Mn Iron Fe Indium In) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:12
-	112	(reduc$7) same ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and (silver Ag) not ((reduc$7) same (metal metallic Tin Sn Manganese Mn Iron Fe Indium In) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and (silver Ag))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 10:51
-	24	(reduc$7) same ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) same (silver Ag) not ((reduc$7) same (metal metallic Tin Sn Manganese Mn Iron Fe Indium In) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and (silver Ag))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:22
-	21	(reduc$7) same ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) same (silver Ag) same (temperature temp "C" celsius degrees) not ((reduc$7) same (metal metallic Tin Sn Manganese Mn Iron Fe Indium In) near3 ion same (substrate glass plate silica) same (heat$7 bak$8) same (oxygen oxidiz$5) and (silver Ag))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 16:28
-	1	20030034732.did.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 19:04

-	1	20030034732.did.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/17 19:04
-	1	20030034732.did.	US-PGPUB	2003/09/17 19:04
-	0	20030034732.did. and additive	US-PGPUB	2003/09/17 19:05
-	1	20030034732.did. and shift$5 near5 color	US-PGPUB	2003/09/17 19:06
-	1	20030034732.did. and shift$5 near5 color and offset$8	US-PGPUB	2003/09/17 19:06
-	428	silver near3 (stained staining) and (glass) near4 (substrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:47
-	32	silver near3 (stained staining) with (electrode cathode anode) and (glass) near4 (substrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:56
-	28	silver near3 (stained staining) with (electrode cathode anode) and (glass) near4 (substrate plate) and (heat$5 fir$5 bak$6) with (substrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:01
-	28	(ag silver) near3 (stained staining) with (electrode cathode anode) and (glass) near4 (substrate plate) and (heat$5 fir$5 bak$6) with (substrate plate) same (silver ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:02
-	0	(ag silver) near3 (stained staining) with (electrode cathode anode) and (glass) near4 (substrate plate) and (heat$5 fired firing bake baked baking fire) with (substrate plate) same (silver ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:02
-	5	(ag silver) near3 (discolor$5 yellowing stained staining) with (electrode cathode anode) and (glass) near4 (substrate plate) and (heat$5 fired firing bake baked baking fire) with (substrate plate) same (silver ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:02
-	1	5216207.pn.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 18:17
-	1	5216207.pn. and (heat$5 fire fired firing baking baked bake)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 18:18
-	1	5216207.pn. and (heat$5 fire fired firing baking baked bake) and glass with (substrate plate)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 18:18
-	1	5216207.pn. and (heat$5 fire fired firing baking baked bake) and glass with (substrate plate) and (silver Ag)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 18:19
-	1	5216207.pn. and (heat$5 fire fired firing baking baked bake) and glass with (substrate plate) and (silver Ag) and (centrigrade celsius degrees)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 18:25
-	1	5216207.pn. and (heat$5 fire fired firing baking baked bake) and glass near5 (substrate plate) and (silver Ag) and (centrigrade celsius degrees)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 18:38
-	1	5216207.pn. and (heat$5 fire fired firing baking baked bake) and glass near5 (substrate plate) and (silver Ag) and (centrigrade celsius degrees) same substrate	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 18:46

-	1	5216207.pn. and (heat$5 fire fired firing baking baked bake) and glass near5 (substrate plate) and (silver Ag) and (centrigrade celsius degrees) same substrate and (oxygen oxidized oxidization oxidize)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 18:51
-	1	5216207.pn. and green adj tape with substrate	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 18:52
-	55	silver near3 (diffusion) with (electrode cathode anode) and (glass) near4 (substrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:56
-	68	silver near3 (diffusion diffuse diffused) with (electrode cathode anode) and (glass) near4 (substrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:57
-	26	silver near3 (diffusion diffuse diffused) with (electrode cathode anode) and (glass) near4 (substrate plate) and (yellowing yellowed discolor$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:57
-	26	silver near3 (diffusion diffuse diffused) with (electrode cathode anode) and (glass) near4 (substrate plate) and (yellowing yellowed discolor$6) and (heat$5 fired fire firing baking baked bake)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:58
-	0	silver near3 (diffusion diffuse diffused) with (electrode cathode anode) and (glass) near4 (substrate plate) and (yellowing yellowed discolor$6) and (heat$5 fired fire firing baking baked bake) with (centigrade celsius degrees near3 "C")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:58
-	0	silver near3 (diffusion diffuse diffused) with (electrode cathode anode) and (glass) near4 (substrate plate) and (yellowing yellowed discolor$6) and (heat$5 fired fire firing baking baked bake) same (centigrade celsius degrees near3 "C")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:58
-	2	silver near3 (diffusion diffuse diffused) with (electrode cathode anode) and (glass) near4 (substrate plate) and (yellowing yellowed discolor$6) and (heat$5 fired fire firing baking baked bake) and (centigrade celsius degrees near3 "C")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 18:59
-	2	silver near3 (diffusion diffuse diffused) with (electrode cathode anode) and (glass) near4 (substrate plate) and (yellowing yellowed discolor$6) and (heat$5 fired fire firing baking baked bake) and (centigrade celsius degrees near3 "C")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:00
-	2	(Ag silver) near3 (diffusion diffuse diffused) with (electrode cathode anode) and (glass) near4 (substrate plate) and (yellowing yellowed discolor$6) and (heat$5 fired fire firing baking baked bake) and (centigrade celsius degrees near3 "C")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:01
-	2	(Ag silver) near3 (diffusion diffuse diffused ion) with (electrode cathode anode) and (glass) near4 (substrate plate) and (yellowing yellowed discolor$6) and (heat$5 fired fire firing baking baked bake) and (centigrade celsius degrees near3 "C")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:06
-	6	6614184.pn. 20030071572.did. 20030030376.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:06

-	0	(6614184.pn. 20030071572.did. 20030030376.did.) and deactiv$6.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:07
-	0	(6614184.pn. 20030071572.did. 20030030376.did.) and (deactiv$6 oxygen oxidiz$6).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:07
-	2	(6614184.pn. 20030071572.did. 20030030376.did.) and (deactiv$6 oxygen oxidiz$6 heat$5 fire fired firing bake baked baking).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:07
-	2	(6614184.pn. 20030071572.did. 20030030376.did.) and (deactiv$6 oxygen oxidiz$6 heat$5 fire fired firing bake baked baking).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:42
-	2	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:42
-	1	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:23
-	1	20030034732.did. and deactiv$8	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 19:43
-	1	20030034732.did. and deactiv$8 and (bak$5 oxygen oxidiz$6)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/21 19:43
-	145	(silver Ag) near5 (electrode cathode anode) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:49
-	46	((silver Ag) near5 (electrode cathode anode) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate)) and (baking baked bake fire fired firing heat$5) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:48
-	46	(silver Ag) near5 (electrode cathode anode) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:49
-	4	(silver Ag) near5 (electrode cathode anode) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) with substrate same (centigrade celsius degrees)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 19:54
-	7	(silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) with substrate same (centigrade celsius degrees)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 20:04

-	3	(silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) same substrate same (centigrade celsius degrees) not ((silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) with substrate same (centigrade celsius degrees))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 20:06
-	5	(silver Ag) near10 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near5 (substrate plate) and (baking baked bake fire fired firing heat$5) same substrate same (centigrade celsius degrees) not ((silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) with substrate same (centigrade celsius degrees))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 20:07
-	2	(silver Ag) near10 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near5 (substrate plate) and (baking baked bake fire fired firing heat$5) same substrate same (centigrade celsius degrees) not ((silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) with substrate same (centigrade celsius degrees)) not ((silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) same substrate same (centigrade celsius degrees) not ((silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) with substrate same (centigrade celsius degrees)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 20:10
-	4	(silver Ag) near10 (cathode electrode anode) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near5 (substrate plate) and (baking baked bake fire fired firing heat$5) same substrate same (centigrade celsius degrees) not ((silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) with substrate same (centigrade celsius degrees)) not ((silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) same substrate same (centigrade celsius degrees) not ((silver Ag) near5 (ion) and (silver ag) with (stained staining discolor$ yellow$5) and (glass) near4 (substrate plate) and (baking baked bake fire fired firing heat$5) with substrate same (centigrade celsius degrees)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 22:18
-	1226	(313/582-587).CCLS.	USPAT; US-PGPUB	2003/09/21 22:19

-	0	("20030034732.did.").PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/02/14 17:57
-	2	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/14 17:57
-	2	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/23 13:54
-	1	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/23 13:54
-	1	20030034732.did. and deactivat$7	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/23 14:18
-	1	20030034732.did. and deactivat$7.clm.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/23 14:18
-	1	substrate same deactivat$4 with glass with metal same (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 10:58
-	1	(substrate substratum sub adj stratum) same deactivat$4 with glass with metal same (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 10:58
-	1	(substrate substratum sub adj stratum) same deactivat$4 with glass with ion same (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:03
-	167	(substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 12:14
-	1	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 11:06
-	1	20030034732.did. and deactivat$5	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 13:34
-	1	20030034732.did. and deactivat$5 same oxidiz$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 11:08
-	1	20030034732.did. and deactivat$5 and oxidiz$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 11:08
-	8	(substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and silver near3 ion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:35
-	0	20030034732.did. and heat$5 with (period time)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:43

-	1	20030034732.did. and (heat$5 bak$4) same (period time)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:44
-	1	20030034732.did. and (period time)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 13:44
-	35	(substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and glass adj2 (substrate substratum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:46
-	5	(substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and glass adj2 (substrate substratum) and display.ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:46
-	5	(substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and (silica glass "SiO.sub.2") adj2 (substrate substratum) and display.ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:50
-	5	(substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and (silica glass "SiO.sub.2") adj2 (substrate substratum) and display.ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:51
-	5	(substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and ((substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and (silica glass "SiO.sub.2") adj2 (substrate substratum) and display.ab,ti,clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:51
-	5	((substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and (silica glass "SiO.sub.2") adj2 (substrate substratum) and display.ab,ti,clm.) and (substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:51
-	5	(substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and (silica glass "SiO.sub.2") adj2 (substrate substratum) and display.ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:51
-	5	((substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag) and (silica glass "SiO.sub.2") adj2 (substrate substratum) and display.ab,ti,clm.) and (substrate substratum sub adj stratum) same heat$5 adj5 (celsius temperature centigrade "C") same (oxygen oxidiz$4) same (silver Ag)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 11:52
-	54	glass adj substrate same hydrogen same nitrogen same (oxidiz$5 reducing)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 13:53

-	2	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 13:45
-	1	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:52
-	1	20030034732.did. and reduc$4 near6 (silver Ag)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 13:45
-	137	glass adj substrate same nitrogen same (oxidiz$5 reducing)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 13:54
-	59	glass adj substrate same nitrogen with (oxidiz$5 reducing)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 15:46
-	1	20030034732.did. and deactivat$5 near5 reduc$5	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 14:11
-	1424	ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 14:29
-	1	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in.) and deactivat$6.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 14:29
-	7	(ohtani-mitsuhiro.in. aoki-masaki.in. hibino-junichi.in. sumida-keisuke.in. asida-hideki.in. fujiwara-shinya.in. marunaka-hideki.in. nakagawa-tadashi.in.) and deactivat$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 14:30
-	1	20030034732.did. and deactivat$6	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 15:13
-	27210	(plasma adj display pdp).ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 16:10
-	2	((plasma adj display pdp).ab,ti,clm.) and deactivat$6 with (substrate substratum sub adj stratum plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 16:15
-	3558	(substrate substratum plate) with deactivat$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 16:16
-	51	(substrate substratum plate) with deactivat$6 with ion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 16:16
-	16	(substrate substratum plate) with deactivat$6 near4 ion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 16:17

-	16	(substrate substratum plate) with deactivat$6 near4 ion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 16:17
-	1973	(substrate plate substratum plate) same (heat$5 baking baked baking) same (air oxygen$5 oxid$7) and (parts near2 million)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:28
-	0	(substrate plate substratum plate) same (heat$5 baking baked baking) same (air oxygen$5 oxid$7) and (parts near2 million) near5 (substrate plate substratum plate) with depth	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:30
-	1	(substrate plate substratum plate) same (heat$5 baking baked baking) same (air oxygen$5 oxid$7) and (parts near2 million) near5 (substrate plate substratum plate) same (depth)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:34
-	1	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:52
-	1	20030034732.did. and deactivat$6 same valence	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:53
-	1	20030034732.did. and deactivat$6 same valence	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:56
-	1	20030034732.did. and deactivat$6 same concentration	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:56
-	1	20030034732.did. and concentration	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:59
-	1	20030034732.did. and manganese	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 16:59
-	1	20030034732.did. and manganese same indium same tin same iron	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:19
-	0	((plasma adj display pdp).ab,ti,clm.) and pur$5 near3 glass adj substrate	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:20
-	39	((plasma adj display pdp).ab,ti,clm.) and pur$5 with glass adj substrate	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:20
-	7	((plasma adj display pdp).ab,ti,clm.) and pure with glass adj substrate	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:21
-	10	((plasma adj display pdp).ab,ti,clm.) and pure near3 (glass silica)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:26
-	1	20030034732.did.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:23
-	0	20030034732.did. and impurit$5	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:23

-	8	((plasma adj display pdp).ab,ti,clm.) and impurit$5 near3 (glass silica)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:45
-	1	20030034732.did. and reduc$5 adj action	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:52
-	1	((plasma adj display pdp).ab,ti,clm.) and deactivat$5 near5 (substrate substratum plate)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:52
-	100	((plasma adj display pdp).ab,ti,clm.) and deactivat$5	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:53
-	0	((plasma adj display pdp).ab,ti,clm.) and deactivat$5 near6 concentration	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 18:07
-	1	20030034732.did. and deactivat$5	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:59
-	1	20030034732.did. and normal	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 17:59
-	71	normal adj glass adj substrate	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 18:00
-	53	normal adj glass adj substrate and reduc$6	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 18:00
-	3	normal adj glass adj substrate and reduc$6 near5 ion	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 18:01
-	10	glass adj substrate near2 surface same (metal metallic) adj ions same concentration	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 18:01
-	2	((plasma adj display pdp).ab,ti,clm.) and deactivat$5 near6 surface	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/03/24 19:58
-	1340	(313/582-587).CCLS.	USPAT; US-PGPUB	2004/03/24 19:58
-	822	(313/636,477R).CCLS.	USPAT; US-PGPUB	2004/03/24 19:58
-	1419	(313/493,512).CCLS.	USPAT; US-PGPUB	2004/03/24 19:58
-	1465	(313/110,311).CCLS.	USPAT; US-PGPUB	2004/03/24 19:58
-	1313	(445/24).CCLS.	USPAT; US-PGPUB	2004/03/24 19:59